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United States Patent [19]

Katoh

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[45] **Date of Patent: ** Sep. 28, 1999**

[54] **MACHINE FOR FORMING A SEMICONDUCTOR WAFER FILM**

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[73] Assignee: **Tokyo Electron Limited**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **29/085,326**

[22] Filed: **Mar. 20, 1998**

[30] **Foreign Application Priority Data**

Sep. 24, 1997 [JP] Japan 9-68687

[51] **LOC (6) Cl.** **15-09**

[52] **U.S. Cl.** **D15/144.1**; D10/75

[58] **Field of Search** D10/75; D15/144.1; 250/492.2

[56] **References Cited**

U.S. PATENT DOCUMENTS

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[57] **CLAIM**

The ornamental design for machine for forming a semiconductor wafer film, as shown.

DESCRIPTION

FIG. **1** is a front elevational view of machine for forming a semiconductor wafer film, showing my new design;

FIG. **2** is a right side elevational view thereof;

FIG. **3** is a left side elevational view thereof;

FIG. **4** is a rear elevational view thereof;

FIG. **5** is a top plan view thereof; and,

FIG. **6** is a bottom plan view thereof.

1 Claim, 3 Drawing Sheets

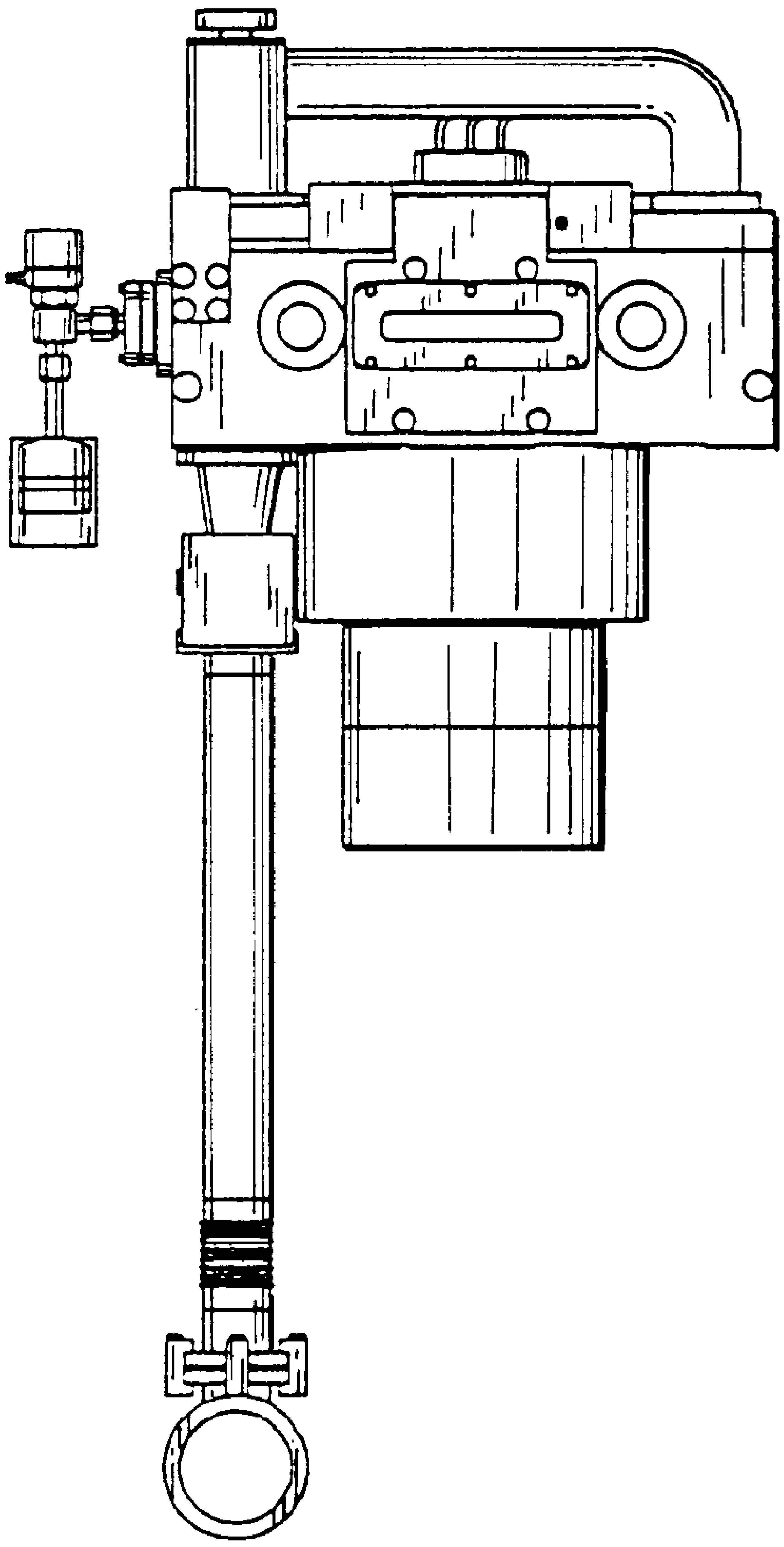

Fig.1

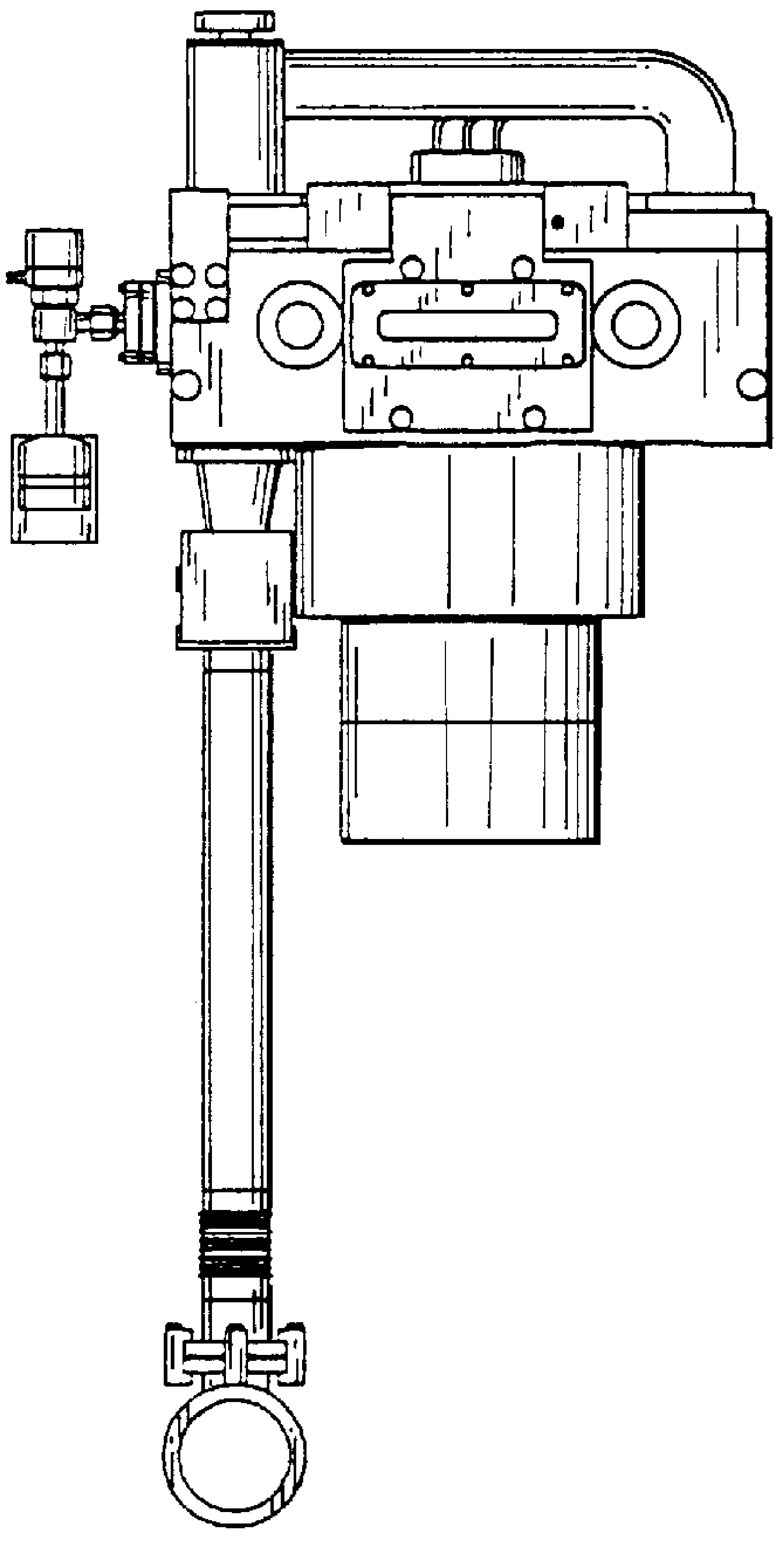

Fig.2

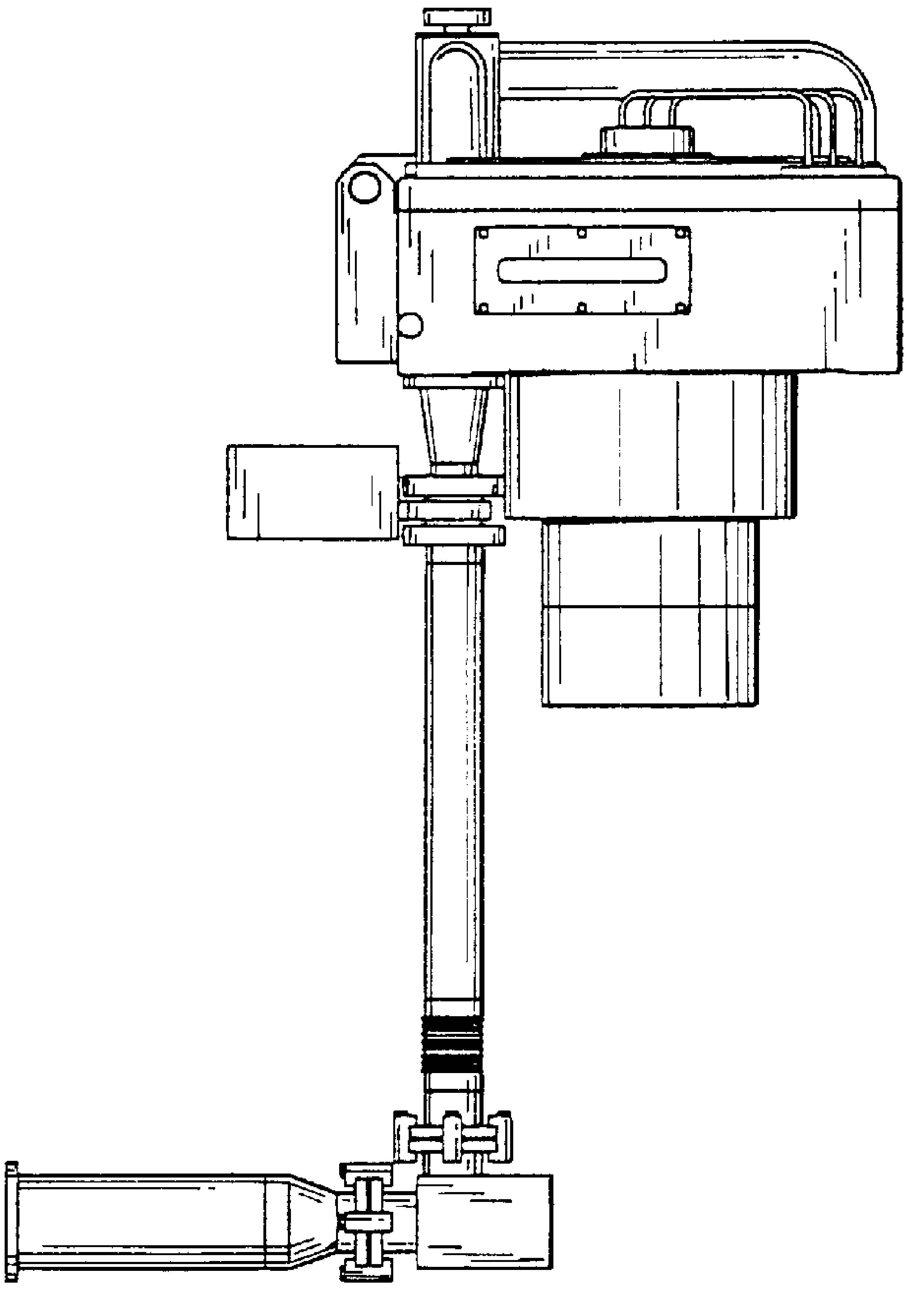

Fig.4

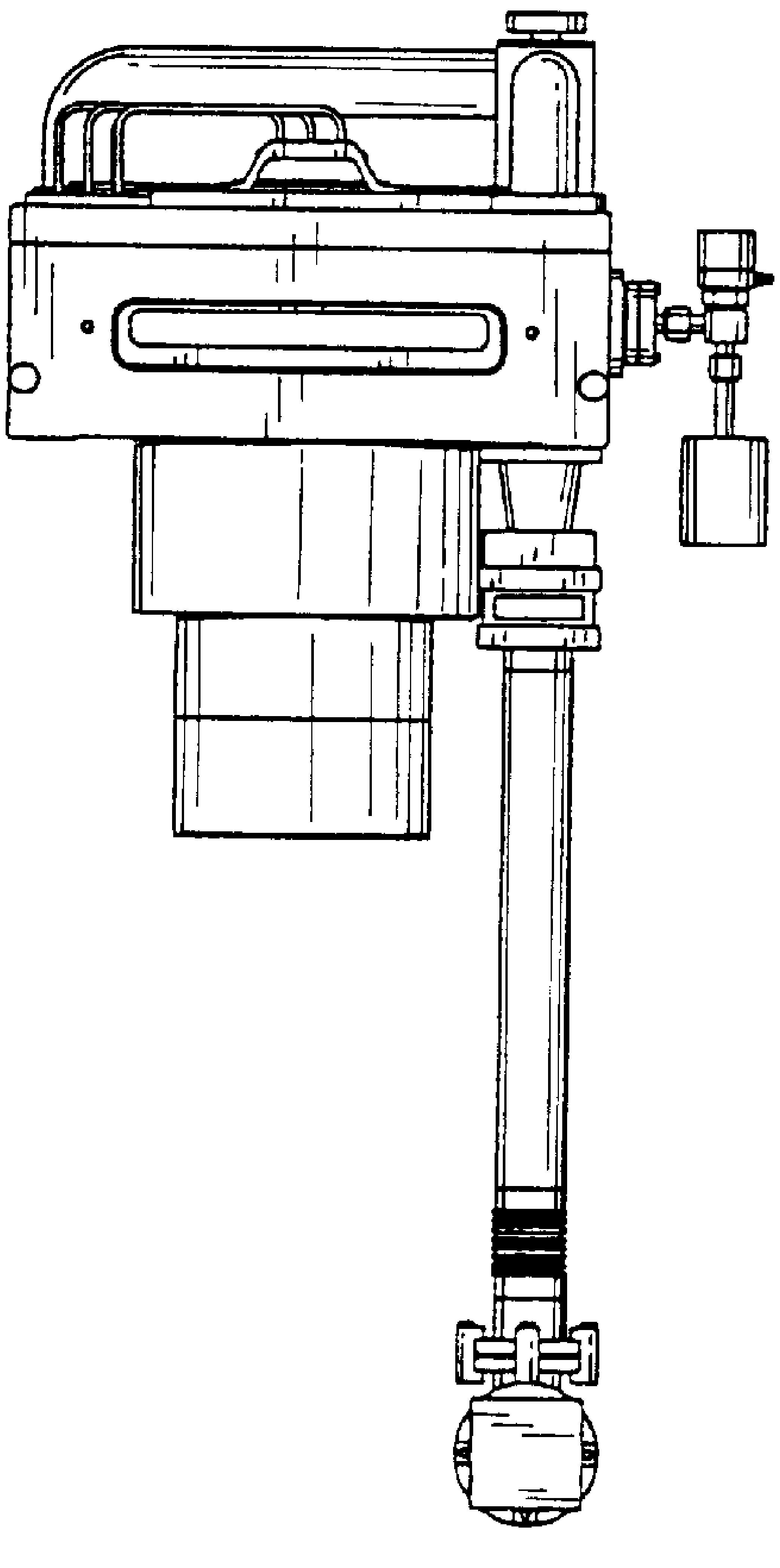

Fig.3

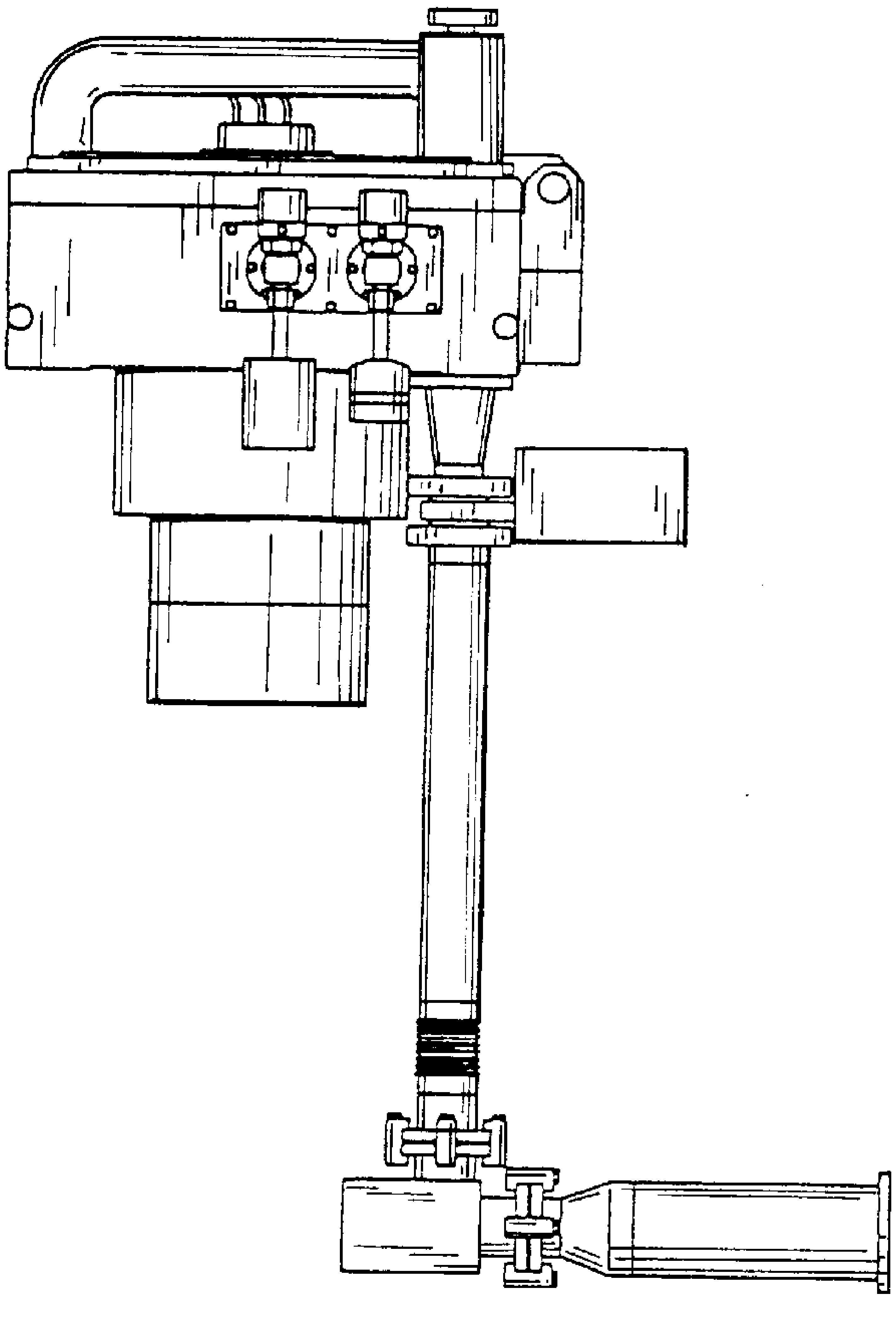

Fig. 5

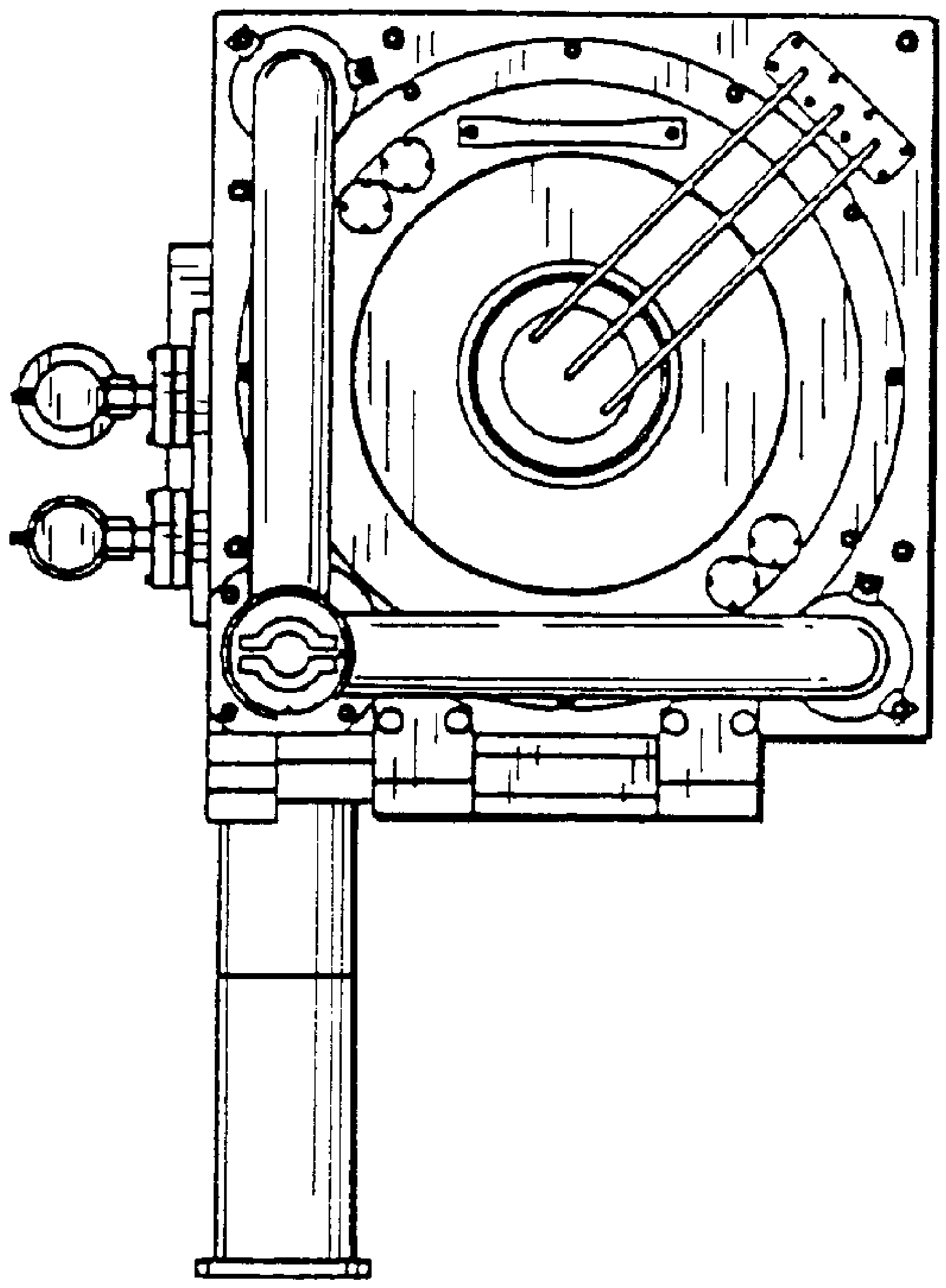

Fig. 6